



01-23-06

ITJ

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re. Appn. Ser. No. 10/733,672

:

Art Unit 2835

Filed 12/11/03

:

Examiner M.V. Dotskoyskiy

Inventors L.S.Mok et al.

:

Atty. Dkt. No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

EXPRESS MAIL CERTIFICATE

Commissioner for Patents  
P.O. Box 1450  
Alexandria Va. 22313-1450  
Sir:

Express Mail Label No. ED 882445249 US  
Date of Deposit 1/20/06

I hereby certify that the following attached paper or fee

Response to 12/21/05, Office Communication - Requirement for restriction,

Information Disclosure Transmittal with reference copies, and,

Replacement Informal Drawing Submission - 9 sheets

Are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, Va. 22313-1450.

Alvin J. Riddles

Typed or printed name of person mailing paper or fee

*Alvin J. Riddles 1/20/06*  
Signature and date of person mailing paper or fee.



Express Mail Label No. ED 882445249 US  
Date of Deposit 1/20/06

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re. Appn. Ser. No. 10/733,672 : Art Unit 2835

Filed 12/11/03 : Examiner M.V. Dotskoyskiy

Inventors L.S.Mok et al. : Atty. Dkt. No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

RESPONSE TO 12/21/05 Office Communication

Commissioner for Patents  
P.O. Box 1450  
Alexandria Va. 22313-1450  
Sir:

Receipt of the 12/21/05 Office Communication; a requirement for restriction; is acknowledged.

The restriction requirement involves a provisional election for examination purposes between:

a category I involving Claims 1 - 14, considered to be drawn to a chip packaging module with

liquid cooling, and,

a category II involving Claim 15, considered to be drawn to a MEMS type fluid pump.

Applicants' provisional election is for category I involving claims 1 - 14.

It is respectfully requested that the following traverse be taken into consideration in a  
determination of finality of the restriction requirement.

In applicants' view the terminology MEMS(Micro-Electro-Mechanical-System) generically  
merely means an electro - mechanical system with micro dimensions, this invention is a system

wherein heat is moved in a fluid and the invention is in the details of the fluid movement.

The MEMS pump is one way of moving the fluid.

The claims may be considered to be in the standard "Ex Parte Jepson" type.

The kind suggestion of the preliminary interview is noted. It would appear that the issues would be clearer once the finality of the restriction is resolved.

This is the first action on the merits, and the first opportunity to advance the enclosed Information Disclosure statement. Replacement informal drawings were advanced in earlier administrative prosecution. The record is not clear whether they are in this file. A copy of the 9 sheet replacement Informal Drawing Submission is provided herewith.

Respectfully submitted,

*Alvin J. Riddles* 1/20/06  
Alvin J. Riddles  
Reg. No. 17862



Express Mail Label No. ED882445249 US

Date of Deposit 1/20/06

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Appn. Ser.No. 10/733,672 : Art Unit 2835  
Filed 12/11/03 : Examiner M.V. Datskovskiy  
Inventors Mok et al. : Atty. Dkt. YOR920030186US1

For CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

INFORMATION DISCLOSURE TRANSMITTAL LETTER

Commissioner For Patents  
U.S. Patent and Trademark Office  
P.O. Box 1450  
Alexandria, Va. 22313-1450

Sir:

Please find enclosed a PTO1449 type listing of article type references with copies which may be relevant to the above identified application. Enclosed also is a listing of US patents which may be relevant to the above identified application.

This listing of references is not a representation that a search has been made, that better references than listed do not exist or that other references are not applicable. Moreover, this listing does not constitute any admission by applicant or applicant's attorney that the information provided herein is necessarily prior art to applicant's invention.

Respectfully submitted,

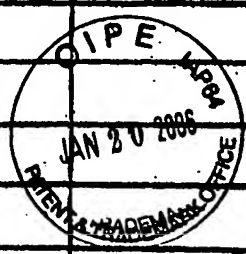
*Alvin J. Riddles* 1/20/06

Alvin J. Riddles  
Reg. No. 17862

LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)	ATTY. DOCKET NO. YOR920030186US1	SERIAL NO. 10/733,672
	APPLICANT MOK ETAL	
	FILING DATE 12/11/03	GROUP 2835

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
AA	3680189					
AB	4046190					
AC	5694295					
AD	6328841					
AE	6391673					
AF	6455398					
AG	6458696					
AH						
AI						
AJ						
AK						



FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
AL							
AM							
AN							
AO							
AP							

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

AR	
AS	
AT	

EXAMINER	DATE CONSIDERED
----------	-----------------

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

LIST OF REFERENCES CITED BY APPLICANT  
(Use several sheets if necessary)

ATTY. DOCKET NO.	SERIAL NO.
YOR920030186151	10/733,672
APPLICANT	
MOK ET AL	
FILED DATE	GROUP
12/11/03	2835

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

GAR	AR	S. J. OK ET AL, "GENERAL, DIRECT CHIP ATTACH MEMS PACKAGING DESIGN WITH HIGH DENSITY AND ASPECT RATIO THROUGH WAFER ELECTRICAL INTERCONNECT," IEEE ELECTRONIC COMPONENTS AND TECH CONF, 2002, PAGES 232-237
GAT	AT	KLINK ET AL, "INNOVATIVE PACKAGING CONCEPTS FOR ULTRA THIN INTEGRATED CIRCUITS," IEEE 2001 ELECTRONIC COMPONENTS AND TECHNOLOGY CONFERENCE, - 5 PAGES
GAU	GAU	ADLER ET AL, "ASSEMBLY OF ULTRATHIN AND FLEXIBLE IC's," IEEE, 2000, PAGES 20-23
GAV	GAU	LANDESBERGER ET AL, "NEW DICING AND THINNING CONCEPT IMPROVES MECHANICAL RELIABILITY OF ULTRATHIN SILICON," 2001 INTERNATIONAL SYMPOSIUM ON ADVANCED PACKAGING MATERIALS, PAGES 92-97
	AR	
	AF	
	AG	
	AH	
	AI	
	AJ	
	AK	
	AR	
	AS	
	AT	

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	